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COOL-BOND
CB7208-E

In situ "Curing"

**Pressure Sensitive
 Electrically Insulating
 Film Adhesive**

IDEAL FOR:

- Component Attach**
- Heat Sink Attach**
- Substrate Attach**

DESCRIPTION:

CB7208-E is a modified version of TP7208 designed to have improved bond strength at elevated temperature. CB7208-E is an aluminum nitride filled, low bond strength thermoplastic film adhesive. It is designed for bonding heat sinks, component, and substrate. CB7208-E has good thermal conductivity. As applied, it provides >50 psi bond strength that will improve to over 300 psi in-situ over time.

TYPICAL PROPERTIES*

Electrical Resistivity (25°C/ 1s Place)	>1x10 ¹⁴ ohm-cm
Dielectric Strength (Volts/mil)	>750
Glass Transition Temp.(°C)	-25
Lap-Shear Strength	>200 psi >1.4 N/mm ²
Device Push-off Strength	>300 psi >2.1 N/mm ²
Hardness (Type)	<40 (A)
Cured Density (gm/cc)	2.2
Thermal Conductivity	25 Btu-in/hr-ft ² -°F 3.6 W/m-°C
Linear Thermal Expansion Coeff. (ppm/°C)	110
Maximum Continuous Operation Temp. (°C)	150

* Properties given are typical values and not intended for use in preparing specifications. The user is advised to evaluate the product in the manner the product is intended to be used in manufacturing and in the final product.

AVAILABILITY:

CB7208-E is available in sheet sizes or as custom preforms. Standard thicknesses are 0.003" and 0.006". Special thicknesses are available.

APPLICATION PROCEDURES:

- (1) Keep at room temperature for 15 minutes before using.
- (2) Cut to desired size. Remove one side of release liner from adhesive.
- (3) Place on substrate or component with rolling finger pressure, then remove the other release liner.
- (4) Place component on substrate with insertion pressure of 10 psi or more. More bond strength will develop in-situ over time during operation.

STRENGTH AFTER CURED

<u>Temperature</u>	<u>Time</u>	<u>Pressure</u>
	Bond Force	
25°C	650 psi	
50°C	550 psi	
75°C	380 psi	
100°C	300 psi	
125°C	250 psi	

SHELF LIFE:

<u>Storage temperature</u>	<u>Shelf Life</u>
0-5°C	1 yr
	in sealed package

CAUTION: This product may cause skin irritation. Avoid skin contact. If contact does occur, wash immediately with soap and water. Please refer to MSDS for more details.

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